

SECTION 27 05 26
GROUNDING AND BONDING FOR COMMUNICATIONS SYSTEMS

PART 1 - GENERAL

1.1 DESCRIPTION

- A. This section specifies general grounding and bonding requirements of telecommunication installations for equipment operations.
- B. "Grounding electrode system" refers to all electrodes required by NEC, as well as including made, supplementary, telecommunications system grounding electrodes.
- C. The terms "connect" and "bond" are used interchangeably in this specification and have the same meaning.

1.2 RELATED WORK

- A. Section 27 05 11, REQUIREMENTS FOR COMMUNICATIONS INSTALLATIONS: General electrical requirements and items that are common to more than one section of Division 27.
- B. Section 27 10 00, STRUCTURED CABLING: Low Voltage power and lighting wiring.
- C. Section 26 41 00, FACILITY LIGHTNING PROTECTION: Requirements for a lightning protection system.

1.3 SUBMITTALS

- A. Submit in accordance with Section 27 05 11, REQUIREMENTS FOR COMMUNICATIONS INSTALLATIONS.
- B. Shop Drawings:
 - 1. Sufficient information, clearly presented, shall be included to determine compliance with drawings and specifications.
 - 2. Include the location of system grounding electrode connections and the routing of aboveground and underground grounding electrode conductors.
- C. Test Reports: Provide certified test reports of ground resistance.
- D. Certifications: Two weeks prior to final inspection, submit four copies of the following to the Resident Engineer:
 - 1. Certification that the materials and installation is in accordance with the drawings and specifications.
 - 2. Certification, by the Contractor, that the complete installation has been properly installed and tested.

1.4 APPLICABLE PUBLICATIONS

Publications listed below (including amendments, addenda, revisions, supplements, and errata) form a part of this specification to the extent referenced. Publications are referenced in the text by the basic designation only.

- A. American Society for Testing and Materials (ASTM):
 - B1-2012.....Standard Specification for Hard-Drawn Copper Wire
 - B8-2011.....Standard Specification for Concentric-Lay-Stranded Copper Conductors, Hard, Medium-Hard, or Soft
- B. Institute of Electrical and Electronics Engineers, Inc. (IEEE):
 - 81-2012.....IEEE Guide for Measuring Earth Resistivity, Ground Impedance, and Earth Surface Potentials of a Ground System
- C. National Fire Protection Association (NFPA):
 - 70-2014.....National Electrical Code (NEC)
- D. Telecommunications Industry Association, (TIA)
 - J-STD-607-B-2011.....Generic Telecommunications Bonding and Grounding (Earthing) for Customer Premises
- E. Underwriters Laboratories, Inc. (UL):
 - 44-2010Thermoset-Insulated Wires and Cables
 - 83-2008Thermoplastic-Insulated Wires and Cables
 - 467-2007Grounding and Bonding Equipment
 - 486A-486B-2013Wire Connectors

PART 2 - PRODUCTS

2.1 GROUNDING AND BONDING CONDUCTORS

- A. Equipment grounding conductors shall be UL 83 insulated stranded copper, except that sizes 6 mm² (10 AWG) and smaller shall be solid copper. Insulation color shall be continuous green for all equipment grounding conductors, except that wire sizes 25 mm² (4 AWG) and larger shall be permitted to be identified per NEC.
- B. Bonding conductors shall be ASTM B8 bare stranded copper, except that sizes 6 mm² (10 AWG) and smaller shall be ASTM B1 solid bare copper wire.
- C. Telecom System Grounding Riser Conductor (Telecommunications Bonding Backbone [TBB]): Telecommunications Grounding Riser shall be in

accordance with J-STD-607B. Use a minimum 50mm² (1/0 AWG) insulated stranded copper grounding conductor unless indicated otherwise.

2.2 GROUND RODS

- A. Copper clad steel, 19 mm (3/4-inch) diameter by 3000 mm (10 feet) long, conforming to UL 467.
- B. Quantity of rods shall be as required to obtain the specified ground resistance and shall only be added to the electrical grounding electrode.

2.3 SPLICES AND TERMINATION COMPONENTS

- A. Components shall meet or exceed UL 467 and be clearly marked with the manufacturer, catalog number, and permitted conductor size(s).

2.4 TELECOMMUNICATION SYSTEM GROUND BUSBARS

- A. Provide solid copper busbar, pre-drilled from two-hole lug connections with a minimum thickness of 6 mm (1/4 inch) for wall and backboard mounting using standard insulators sized as follows:
 - 1. Telecom Grounding Busbar (TGB): 508 mm x 50 mm (18 inches x 2 inch).
 - 2. Telecom Main Grounding Busbar (TMGB): 610 mm x 101 mm (24 inches x 4 inch).

2.5 GROUND CONNECTIONS

- A. Below Grade: Exothermic-welded type connectors.
- B. Above Grade:
 - 1. Bonding Jumpers: compression type connectors, using zinc-plated fasteners and external tooth lockwashers.
 - 2. Ground Busbars: Two-hole compression type lugs using tin-plated copper or copper alloy bolts and nuts.
 - 3. Rack and Cabinet Ground Bars: one-hole compression-type lugs using zinc-plated or copper alloy fasteners.
- C. Cable Shields: Make ground connections to multipair communications cables with metallic shields using shield bonding connectors with screw stud connection.

2.6 EQUIPMENT RACK AND CABINET GROUND BARS

- A. Provide solid copper ground bars designed for mounting on the framework of open or cabinet-enclosed equipment racks with minimum dimensions of 4 mm thick by 19 mm wide (3/8 inch x 3/4 inch).

2.7 GROUND TERMINAL BLOCKS

- A. At any equipment mounting location (e.g. backboards and hinged cover enclosures) where rack-type ground bars cannot be mounted, provide screw lug-type terminal blocks.

2.8 SPLICE CASE GROUND ACCESSORIES

- A. Splice case grounding and bonding accessories shall be supplied by the splice case manufacturer when available. Otherwise, use 16 mm² (6 AWG) insulated ground wire with shield bonding connectors.

PART 3 - EXECUTION

3.1 GENERAL

- A. Ground in accordance with the NEC, as shown on drawings, and as hereinafter specified.
- B. Equipment Grounding: Metallic structures (including ductwork and building steel), enclosures, raceways, junction boxes, outlet boxes, cabinets, machine frames, and other conductive items in close proximity with electrical circuits shall be bonded and grounded.

3.2 INACCESSIBLE GROUNDING CONNECTIONS

- A. Make grounding connections, which are buried or otherwise normally inaccessible (except connections for which periodic testing access is required) by exothermic weld.

3.3 SECONDARY EQUIPMENT AND CIRCUITS

- A. Conduit Systems:
 - 1. Ground all metallic conduit systems and wireways. All metallic conduit systems shall contain an equipment grounding conductor.
 - 2. Non-metallic conduit systems shall contain an equipment grounding conductor, except that non-metallic feeder conduits which carry a grounded conductor from exterior transformers to interior or building-mounted service entrance equipment need not contain an equipment grounding conductor.
 - 3. Conduit containing only a grounding conductor, and which is provided for mechanical protection of the conductor, shall be bonded to that conductor at the entrance and exit from the conduit.
- B. Boxes, Cabinets, Enclosures, and Panels:
 - 1. Bond the equipment grounding conductor to each pullbox, junction box, outlet box, device box, cabinets, and other enclosures through which the conductor passes (except for special grounding systems for intensive care units and other critical units shown).

2. Provide lugs in each box and enclosure for equipment grounding conductor termination.

3.4 CORROSION INHIBITORS

- A. When making ground and ground bonding connections, apply a corrosion inhibitor to all contact surfaces. Use corrosion inhibitor appropriate for protecting a connection between the metals used.

3.5 TELECOMMUNICATIONS SYSTEM

- A. Bond telecommunications system grounding equipment to the electrical grounding electrode system directly from the TMGB.
- B. Furnish and install all wire and hardware required to properly ground, bond and connect communications raceway, cable tray, metallic cable shields, and equipment to a ground source.
- C. Ground bonding jumpers shall be continuous with no splices. Use the shortest length of bonding jumper possible.
- D. Provide ground paths that are permanent and continuous with a resistance of 1 ohm or less from raceway, cable tray, and equipment connections to the building grounding electrode. The resistance across individual bonding connections shall be 10 milli ohms or less.
- E. Below-Grade Grounding Connections: When making exothermic welds, wire brush or file the point of contact to a bare metal surface. Use exothermic welding cartridges and molds in accordance with the manufacturer's recommendations. After welds have been made and cooled, brush slag from the weld area and thoroughly cleaned the joint area. Notify the Resident Engineer prior to backfilling any ground connections.
- F. Above-Grade Grounding Connections: When making bolted or screwed connections to attach bonding jumpers, remove paint to expose the entire contact surface by grinding where necessary; thoroughly clean all connector, plate and other contact surfaces; and apply an appropriate corrosion inhibitor to all surfaces before joining.
- G. Bonding Jumpers:
 1. Use insulated ground wire of the size and type shown on the Drawings or use a minimum of 16 mm² (6 AWG) insulated copper wire.
 2. Assemble bonding jumpers using insulated ground wire terminated with compression connectors.

3. Use compression connectors of proper size for conductors specified. Use connector manufacturer's compression tool.

H. Bonding Jumper Fasteners:

1. Conduit: Fasten bonding jumpers using screw lugs on grounding bushings or conduit strut clamps, or the clamp pads on push-type conduit fasteners. When screw lug connection to a conduit strut clamp is not possible, fasten the plain end of a bonding jumper wire by slipping the plain end under the conduit strut clamp pad; tighten the clamp screw firmly. Where appropriate, use zinc-plated external tooth lockwashers.
2. Wireway and Cable Tray: Fasten bonding jumpers using zinc-plated bolts, external tooth lockwashers, and nuts. Install protective cover, e.g., zinc-plated acorn nuts on any bolts extending into wireway or cable tray to prevent cable damage.
3. Ground Plates and Busbars: Fasten bonding jumpers using two-hole compression lugs. Use tin-plated copper or copper alloy bolts, external tooth lockwashers, and nuts.

3.6 COMMUNICATION ROOM GROUNDING

A. Telecommunications Ground Busbars:

1. Provide communications room telecommunications ground busbar hardware at 950 mm (18 inches) at locations indicated on the Drawings.
2. Connect the telecommunications room ground busbars to other room grounding busbars as indicated on the Grounding Riser diagram.

B. Telephone-Type Cable Rack Systems: aluminum pan installed on telephone-type cable rack serves as the primary ground conductor within the communications room. Make ground connections by installing the following bonding jumpers:

1. Install a 16 mm² (6 AWG) bonding between the telecommunications ground busbar and the nearest access to the aluminum pan installed on the cable rack.
2. Use 16 mm² (6 AWG) bonding jumpers across aluminum pan junctions.

C. Self-Supporting and Cabinet-Mounted Equipment Rack Ground Bars:

1. When ground bars are provided at the rear of lineup of bolted together equipment racks, bond the copper ground bars together using solid copper splice plates supplied by the ground bar manufacturer.

2. Bond together nonadjacent ground bars on equipment racks and cabinets with 16 mm² (6 AWG) insulated copper wire bonding jumpers attached at each end with compression-type connectors and mounting bolts.
 3. Provide a 16 mm² (6 AWG) bonding jumper between the rack and/or cabinet ground busbar and the aluminum pan of an overhead cable tray or the raised floor stringer as appropriate.
- D. Backboards: Provide a screw lug-type terminal block or drilled and tapped copper strip near the top of backboards used for communications cross-connect systems. Connect backboard ground terminals to the aluminum pan in the telephone-type cable tray using an insulated 16 mm² (16 AWG) bonding jumper.
- E. Other Communication Room Ground Systems: Ground all metallic conduit, wireways, and other metallic equipment located away from equipment racks or cabinets to the cable tray pan or the telecommunications ground busbar, whichever is closer, using insulated 16 mm² (6 AWG) ground wire bonding jumpers.

3.7 COMMUNICATIONS CABLE GROUNDING

- A. Bond all metallic cable sheaths in multipair communications cables together at each splicing and/or terminating location to provide 100 percent metallic sheath continuity throughout the communications distribution system.
1. At terminal points, install a cable shield bonding connector provide a screw stud connection for ground wire. Use a bonding jumper to connect the cable shield connector to an appropriate ground source like the rack or cabinet ground bar.
 2. Bond all metallic cable shields together within splice closures using cable shield bonding connectors or the splice case grounding and bonding accessories provided by the splice case manufacturer. When an external ground connection is provided as part of splice closure, connect to an approved ground source and all other metallic components and equipment at that location.

3.8 COMMUNICATIONS CABLE TRAY SYSTEMS (NOT USED)

3.9 COMMUNICATIONS RACEWAY GROUNDING

- A. Conduit: Use insulated 16 mm² (6 AWG) bonding jumpers to ground metallic conduit at each end and to bond at all intermediate metallic enclosures.

- B. Wireway: use insulated 16 mm² (6 AWG) bonding jumpers to ground or bond metallic wireway at each end at all intermediate metallic enclosures and across all section junctions.
- C. Cable Tray Systems: Use insulated 16 mm² (6 AWG) bonding jumpers to ground cable tray to column-mounted building ground plates (pads) at each end and approximately every 16 meters (50 feet).

3.10 GROUND RESISTANCE

- A. Grounding system resistance to ground shall not exceed 5 ohms. Make necessary modifications or additions to the grounding electrode system for compliance without additional cost to the Government. Final tests shall assure that this requirement is met.
- B. Resistance of the grounding electrode system shall be measured using a four-terminal fall-of-potential method as defined in IEEE 81. Ground resistance measurements shall be made before the electrical distribution system is energized and shall be made in normally dry conditions not less than 48 hours after the last rainfall. Resistance measurements of separate grounding electrode systems shall be made before the systems are bonded together below grade. The combined resistance of separate systems may be used to meet the required resistance, but the specified number of electrodes must still be provided.
- C. Below-grade connections shall be visually inspected by the Resident Engineer prior to backfilling. The Contractor shall notify the Resident Engineer 24 hours before the connections are ready for inspection.

3.11 GROUND ROD INSTALLATION

- A. Drive each rod vertically in the earth, not less than 3000 mm (10 feet) in depth.
- B. Where permanently concealed ground connections are required, make the connections by the exothermic process to form solid metal joints. Make accessible ground connections with mechanical pressure type ground connectors.
- C. Where rock prevents the driving of vertical ground rods, install angled ground rods or grounding electrodes in horizontal trenches to achieve the specified resistance.

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